

SAMXON ELECTRONICS COMPONENTS CO, LTD PRODUCT SPECIFICATION 規格書

CUSTOMER :

(**客戶**): 志盛翔

DATE :

(日期):2020-1-17

CATEGORY (品名)	: ALUMINUM ELECTROLYTIC CAPACITORS	
DESCRIPTION (型号)	: SK $63V220\mu F(\phi 10X16)$	
VERSION (版本)	: 01	
Customer P/N	:	
SUPPLIER	:	

SUPPLI	ER		CUSTOMER				
PREPARED (拟定)	CHECKED (审核)	Α	PPROVAL (批准)	SIGNATURE (签名)			
赵安平	刘渭清						

	SI	PECIFICATIO	ALTERNATION HISTORY RECORDS				
Rev.	Date	SK SERIES Mark	Page	Contents	Purpose	Drafter	Approver
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	SAMXON ELECTRO COMPANY LIMIT												
able	e 1 Product Dimensi	ions and	d Cha	racteristics	5						Unit:	mm	
	Safety vent for $\geq \varphi$ 6.3	$\frac{\alpha}{\beta} = \frac{1}{2} + \frac{1}$							β =1.0	lat			
No.	SAMXON Part No.	WV (Vdc)	Cap. (µF)	Cap. tolerance	Temp. range(℃)	tan δ (120Hz 20℃)	Leakage Current (µA,2min)	Max Ripple Current at 105 °C 100kHz	Impedance at 20°C 100kHz (Ωmax)	Load lifetime (Hrs)	nension (mm) F	фd	Sleeve

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ELECTROLYTIC CAPACITOR SPECIFICATION SK SERIES

1. Application

This specification applies to polar Aluminum electrolytic capacitor (foil type) used in electronic equipment. Designed capacitor's quality meets IEC60384.

2. Part Number System

eries	Cap(MFD)	Code	Tolerance (%)	Code	Voltage (W.V.)	Code	Case	Size	Feature (SAMXON Product L	
SM KF SS	0.1	104	± 5	J	2 2.5	0D 0E	Diameter() 3 3.5 4	B	Radial bulk	RR	For internal use only (The product lines	
KS GS KM	0.22	224	±10	к	4 6.3	0G 0J	4 5 6.3		Ammo Tap	ing	we have H,A,B,C,D, E,M or 0,1,2,3,4,5,9	
KG OM ZM	0.33	334	±15	L	8 10	0K 1A 1B	8 10 12.5	<u> </u>	2.0mm Pitch	Π		
ZS GF SF	0.47	474	±20	м	12.5 16 20	1C 1D	13 13.5 14	J V 4	2.5mm Pitch 3.5mm Pitch	TU TV		
GT GK GE	2.2	105 225			25 30	1E 1I	14.5 16 16.5	A K 7	5.0mm Pitch	тс	Sleeve Material	Cod P
GD GC RS	3.3	335	±30 -40	N	32 35	13 1V	18 18.5 20 22	L 8 M	Lead Cut & I			
RF RL RR	4.7	475	-20	w	40 42	1G 1M	22 25 30 34	응	СВ-Туре	СВ		
RT RE RD	10	106	0	^	50 57	1H 1L	35	W Q R	СЕ-Туре	CE		
RH BD RA	22	226	-20 +10	c	63 71	1J 1S	42 45 51	4 6 S	НЕ-Туре	HE		
RB RC FA	33	336	-20 +40	×	75 80 85	1T 1K 1R	63.5 76 80		КД-Туре	КD		
NP NH RW	47	476	-20 +50	s	90 100	19 2A	90 100 Len.(mm)		FD-Type	FD		
RY LP AP	100	107	-10 0	в	120 125	20 28	4.5 5 5.4	45 05 54 07	EH-Type	EH		
QP DP TP	220	227	-10 +20	×	150 160	2Z 2C	7.7 10.2	77 T2	PCB Term	sw		
HP UP KP	330	337	-10 +30	Q	180 200	2P 2D	11 11.5 12 12.5	11 1A 12	Snap-in	sx		
EP FP SP	470 2200	477 228	-10 +50	т	215 220	22 2N	13.5	1B 13 1C		sz		
VP GP WR	22000	229	+10	E	230 250	23 2E	20 25 29.5	20 25 2J	Lug	SG		
WU WT WX	33000	339	-5 +15	F	275 300 310	2T 2I 2R	30 31.5 35	30 3A 35		05		
WF WS WH	47000	479	+20 0	G	315 330	2F 2U	35.5 50 80	3E 50 80		06		
WL WB /SS	100000	10T	+20	R	350 360	2V 2V 2X		1L 1K 1M	Screw	т5		
/NS /KS	150000	15T	+30	0 1	375 385	2Q 2Y		1N 1P 1Q		т6		
/KM /RL /NH /78	220000	22T	+50 +5 +15	z	400 420	2G 2M	150 155 160	1E		D5 D6		
/ZS /RF	330000	33Т	+15 +5 +20	D	450 500	2W 2H	160 165 170 180	110		00		
	1000000	10M	+10 +50	Y	550 600	25 26	190 200 215	2A				
	1500000	15M	+10 +30	н	630	2J	210 220 240	2M 2N 2Q				
	2200000 3300000	22M 33M			-		210 220 240 250 260 270	2R 2S 2T				

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ELECTROLYTIC CAPACITOR SPECIFICATION SK SERIES

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3. Construction

Single ended type to be produced to fix the terminals to anode and cathode foil, and wind together with paper, and then wound element to be impregnated with electrolyte will be enclosed in an aluminum case. Finally sealed up tightly with end seal rubber, then finished by putting on the vinyl sleeve.



No	Component	Material
1	Lead line	Tinned CP wire (Pb Free)
2	Terminal	Aluminum wire
3	Sealing Material	Rubber
4	Al-Foil (+)	Formed aluminum foil
5	Al-Foil (-)	Etched aluminum foil or formed aluminum foil
6	Case	Aluminum case
7	Sleeve	PET
8	Separator	Electrolyte paper

4. Characteristics

Standard atmospheric conditions

Unless otherwise specified, the standard range of atmospheric conditions for making measurements and tests are as follows:

Ambient temperature	:15°C to 35°C
Relative humidity	: 45% to 85%
Air Pressure	: 86kPa to 106kPa

If there is any doubt about the results, measurement shall be made within the following conditions:

Ambient temperature	$: 20^{\circ}C \pm 2^{\circ}C$
Relative humidity	: 60% to 70%
Air Pressure	: 86kPa to 106kPa

Operating temperature range

The ambient temperature range at which the capacitor can be operated continuously at rated voltage See table 1 temperature range.

As to the detailed information, please refer to table 2.

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	ITEM				PERFC	RMANC	Έ			
	Rated voltage									
	(WV)	WV (V.DC)	6.3	10	16	25	35	50	63	100
4.1		SV (V.DC)	8	13	20	32	44	63	79	125
	Surge voltage (SV)									
4.2	Nominal capacitance (Tolerance)	<condition> Measuring F Measuring V Measuring T <criteria> Shall be with</criteria></condition>	requenc oltage 'emperat	: N ure : 20)±2℃	than 0.5V				
4.3	Leakage current	<condition> Connecting t minutes, and <criteria> Refer to Tabl</criteria></condition>	he capae then, me		-		istor (1	$k\Omega \pm 10$	Ω) in se	eries for
4.4	tanδ	<condition> See 4.2, Norr <criteria> Refer to Tabl</criteria></condition>	m Capac	itance, fo	or measu	ing frequ	ency, vo	oltage and	l tempera	ature.
4.5	Terminal strength	0.51 Over 0. <criteri< td=""><td>ength of capacitor rength of apacitor, $2 \sim 3 \sec \alpha$ er of lea <u>nm and 1</u> 5mm to a></td><td>r, applied f Termina applied f onds, and d wire less 0.8mm</td><td>force to als. Force to b then ber Tens</td><td>ent the te</td><td>rminal (1 D° to its o N</td><td>l~4 mm f original j Bending (kg 2.5 (0 5 (0</td><td>from the position v force N gf) 0.25) .51)</td><td>rubber) f within 2-</td></criteri<>	ength of capacitor rength of apacitor, $2 \sim 3 \sec \alpha$ er of lea <u>nm and 1</u> 5mm to a >	r, applied f Termina applied f onds, and d wire less 0.8mm	force to als. Force to b then ber Tens	ent the te	rminal (1 D° to its o N	l~4 mm f original j Bending (kg 2.5 (0 5 (0	from the position v force N gf) 0.25) .51)	rubber) f within 2-

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ELECTROLYTIC CAPACITOR SPECIFICATION SK SERIES

		STEP	Testing	g Tempe	rature(°C			Time		
		1		20 ± 2		-	e to reach	thermal e	quilibriu	m
		2	-	40(-25)	± 3			thermal e		
		3		20 ± 2		Tim	e to reach	thermal e	quilibriu	m
		4		$105\pm$	2			thermal e	•	
		5		20 ± 2	2	-		thermal e	•	
	Temperature	<criteria></criteria>								
	characteristi	a. tanδ	shall be w	ithin the	e limit of	tem 4.4				
4.6	cs		leakage cu	rrent me	easured sl	nall not	more that	an 8 times	s of its s	pecified
		value								
			ep 5, tan δ							
			C, impedan	1	1				1	
		Working Vo	-	6.3	10	16	25	35	50	63
		Z-25°C/Z	+20°C	2	2	2	2	2	2	2
		<condition></condition>	1. (JE(260204	412		TI	•, •	. 1.	
4.7	Load life	at a te for Ta workir time at The re	ding to IEC mperature of able1. (The ng voltage) t atmospher esult should	of 105 C sum of Then th ric condi	2 ± 2 with DC and rine productions.	DC bia pple pe should	s voltage ak voltag l be teste	plus the rate shall not	ted rippl t exceed	e currei the rate
	test	<crite< td=""><td></td><td> 1 11</td><td> 1 f.</td><td>11!</td><td>· · · ·</td><td> 4 -</td><td></td><td></td></crite<>		1 11	1 f.	11!	· · · ·	4 -		
			naracteristic		Value in 4					
						snan	oc satist	icu		
		-	age current			25% of	initial v	alue(631($V \cdot \leq + \gamma$	30%)
		Capa	citance Ch	ange	Within \pm			alue(6.3,10 specified		30%)
		Capa tanδ	citance Ch	ange	Within \pm Not more	than 20	0% of the	e specified	value.	30%)
		Capa tanδ	0	ange	Within \pm Not more	than 20	0% of the		value.	30%)

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		<criteria></criteria>
		The characteristic shall meet the following requirements.
		Leakage current Value in 4.3 shall be satisfied
1.0	Shelf	Capacitance Change Within $\pm 25\%$ of initial value(6.3,10V: $\leq \pm 30\%$)
4.8	life	tan δ Not more than 200% of the specified value.
	test	Appearance There shall be no leakage of electrolyte.
		Remark: If the capacitors are stored more than 1 year, the leakage current may
		increase. Please apply voltage through about 1 k Ω resistor, if necessary.
		<pre><condition></condition></pre>
		Applied a surge voltage to the capacitor connected with a (100 \pm 50)/C _R (k Ω) resistor.
		The capacitor shall be submitted to 1000 cycles, each consisting of charge of 30 \pm 5s.
		followed discharge of 5 min 30s.
		The test temperature shall be 15~35°C.
		C_R : Nominal Capacitance (μ F)
	Surgo	<criteria></criteria>
4.9	Surge test	Leakage current Not more than the specified value.
	1051	Capacitance Change Within $\pm 15\%$ of initial value.
		tan δ Not more than the specified value.
		Appearance There shall be no leakage of electrolyte.
		Attention:
		This test simulates over voltage at abnormal situation only. It is not applicable to such
		over voltage as often applied.
4.10	Vibration test	The following conditions shall be applied for 2 hours in each 3 mutually perpendicular directions. Vibration frequency range : 10Hz ~ 55Hz Peak to peak amplitude : 1.5mm Sweep rate : 10Hz ~ 55Hz ~ 10Hz in about 1 minute Mounting method: The capacitor with diameter greater than 12.5mm or longer than 25mm must be fixed in place with a bracket. 4mm or less Within 30°
		To be soldered Criteria> After the test, the following items shall be tested: Inner construction No intermittent contacts, open or short circuiting. No damage of tab terminals or electrodes. Appearance No mechanical damage in terminal. No leakage of electrolyte or swelling of the case. The markings shall be legible.

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		<condition></condition>	. 1 1 .1	C 11 '	1				
		The capacitor shall be test		e following co : 245±3°C	ondition	IS:			
		Soldering temperature Dipping depth		: 245±3°C : 2mm					
	Solderability	Dipping speed		211111 : 25±2.5mm/s					
4.11	test	Dipping speed Dipping time		25 ± 2.5 mm/s 3 ± 0.5 s					
		<criteria></criteria>		. 5±0.55					
		Coating quality A minimu immersed			of 95%	of the surfac	e being		
		<condition></condition>							
		Terminals of the capac	tor shall be	e immersed int	o solde	r bath at			
		260 ± 5 °C for 10 ± 1 sec	onds or 400	$\pm 10^{\circ}$ C for 3 ⁺¹ ₋₀	second	ls to 1.5~2.0	mm from		
		body of capacitor.							
	Resistance to	Then the capacitor sha			l tempe	rature and n	ormal		
4.12	solder heat test	humidity for 1~2 hour < Criteria >	s before me	asurement.					
	test	Leakage current	Not	more than the	specifi	ied value.			
		Capacitance Change	Wit	hin $\pm 10\%$ of	initial	value.			
		tanδ Not me		more than the	specifi	ied value.			
		Appearance	The	re shall be no	leakage	e of electroly	yte.		
		<condition></condition>							
		Temperature Cycle:Accor				ods, capacito	or shall be		
		placed in an oven, the cor		rding as below			I		
		Temperature			Т	lime			
		(1)+20°C		:	≤ 3	Minutes			
	Change of	(2)Rated low tempera	ature (-40℃)(-25°C)	30 ± 2	Minutes			
4.13	temperature	(3)Rated high temper	rature (+105	°C)	30 ± 2	Minutes			
	test	(1) to (3)=1 cycle, tot	tal 5 cycle						
		<criteria></criteria>							
		The characteristic shall m	eet the follo	wing requiren	nent				
				wing requiren re than the spe		value.			
		The characteristic shall m	Not mo		ecified				
		The characteristic shall m Leakage current	Not mo	re than the spe	ecified ecified	value.			
		The characteristic shall m Leakage current tanδ	Not mo	re than the spe re than the spe	ecified ecified	value.			
		The characteristic shall m Leakage current tanδ Appearance <condition> Humidity Test:</condition>	Not mo Not mo There s	re than the spe re than the spe hall be no leak	ecified ecified cage of	value. electrolyte.			
		The characteristic shall m Leakage current tanδ Appearance <condition> Humidity Test: According to IEC60384-4</condition>	Not mo Not mo There s	re than the spe re than the spe hall be no leak	ecified ecified cage of cor shal	value. electrolyte.			
		The characteristic shall m Leakage current tanδ Appearance <condition> Humidity Test: According to IEC60384-4 hours in an atmosphere of</condition>	Not mo Not mo There s 4No.4.12 me f 90~95%R	re than the spe re than the spe hall be no leak	ecified ecified cage of cor shal	value. electrolyte.			
		The characteristic shall m Leakage current tanδ Appearance <condition> Humidity Test: According to IEC60384-4 hours in an atmosphere of meet the following required</condition>	Not mo Not mo There s 4No.4.12 me f 90~95%R	re than the spe re than the spe hall be no leak	ecified ecified cage of cor shal	value. electrolyte.			
4.14	Damp heat	The characteristic shall m Leakage current tanδ Appearance <condition> Humidity Test: According to IEC60384-4 hours in an atmosphere of meet the following require <criteria></criteria></condition>	Not mo Not mo There s 4No.4.12 me f 90~95%R ement.	re than the spe re than the spe hall be no leak ethods, capacit H .at $40\pm2^{\circ}$ C	ecified ecified kage of or shall , the ch	value. electrolyte. l be exposed aracteristic			
4.14	Damp heat test	The characteristic shall m Leakage current tanδ Appearance Condition> Humidity Test: According to IEC60384-4 hours in an atmosphere of meet the following require Criteria> Leakage current	Not mo Not mo There s 4No.4.12 me f 90~95%R ement.	re than the spe re than the spe hall be no leak ethods, capacit H .at $40\pm2^{\circ}$ than the specif	ecified ecified xage of cor shall , the ch	value. electrolyte. l be exposed aracteristic			
4.14	-	The characteristic shall m Leakage current tanδ Appearance <condition> Humidity Test: According to IEC60384-4 hours in an atmosphere of meet the following require <criteria> Leakage current Capacitance Change</criteria></condition>	Not mo Not mo There s 4No.4.12 me f 90~95%R ement. Not more Within ±	re than the spe re than the spe hall be no leak ethods, capacit H .at $40\pm2^{\circ}$ than the specif 20% of initial	ecified ecified cage of cor shall , the ch fied val value.	value. electrolyte. l be exposed aracteristic ue.	change sha		
4.14	-	The characteristic shall m Leakage current tanδ Appearance Condition> Humidity Test: According to IEC60384-4 hours in an atmosphere of meet the following require Leakage current Capacitance Change tanδ	Not mo Not mo There s No.4.12 me f 90~95%R ement. Not more Within ±	re than the spe re than the spe hall be no leak ethods, capacit H .at $40\pm 2^{\circ}$ C than the specif 20% of initial than 120% of	ecified cage of cor shall , the ch fied val value. the spec	value. electrolyte. l be exposed aracteristic ue. cified value.	change sha		
4.14	-	The characteristic shall m Leakage current tanδ Appearance <condition> Humidity Test: According to IEC60384-4 hours in an atmosphere of meet the following require <criteria> Leakage current Capacitance Change</criteria></condition>	Not mo Not mo There s No.4.12 me f 90~95%R ement. Not more Within ±	re than the spe re than the spe hall be no leak ethods, capacit H .at $40\pm2^{\circ}$ than the specif 20% of initial	ecified cage of cor shall , the ch fied val value. the spec	value. electrolyte. l be exposed aracteristic ue. cified value.	change sha		

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4.15	Vent test	22.4 or less	ith its polar able is appl rrent (A) 1 10 o dangerous	rity reversed ied.	l to a DC p	ower source	e. Then a
4.16	Maximum permissible (ripple current)	<condition> The maximum permissible ri at 120Hz and can be applied Table-1 The combined value of D.C rated voltage and shall not r Frequency Multipliers: Coefficient Freq. Cap. (μ F) 33~270 330~680 820~1800 2200~8200</condition>	l at maxim voltage an	um operatin d the peak A	g temperati	ıre	ceed the

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5. It refers to the latest document of "Environment-related Substances standard" (WI-HSPM-QA-072).

	Substances					
	Cadmium and cadmium compounds					
Heavy metals	Lead and lead compounds					
ficavy metals	Mercury and mercury compounds					
	Hexavalent chromium compounds					
	Polychlorinated biphenyls (PCB)					
Chloinated	Polychlorinated naphthalenes (PCN)					
organic	Polychlorinated terphenyls (PCT)					
compounds	Short-chain chlorinated paraffins(SCCP)					
	Other chlorinated organic compounds					
	Polybrominated biphenyls (PBB)					
Brominated .	Polybrominated diphenylethers(PBDE) (including					
organic	decabromodiphenyl ether[DecaBDE])					
compounds	Other brominated organic compounds					
Tributyltin comp	oounds(TBT)					
Triphenyltin con	npounds(TPT)					
Asbestos						
Specific azo compounds						
Formaldehyde						
Beryllium oxide						
Beryllium copp	er					
Specific phthalates (DEHP,DBP,BBP,DINP,DIDP,DNOP,DNHP)						
Hydrofluorocarbon (HFC), Perfluorocarbon (PFC)						
Perfluorooctane	sulfonates (PFOS)					
Specific Benzotr	iazole					

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Attachment: Application Guidelines

1.Circuit Design

- 1.1 Operating Temperature and Frequency Electrolytic capacitor electrical parameters are normally specified at 20°C temperature and 120Hz frequency. These parameters vary with changes in temperature and frequency. Circuit designers should take these changes into consideration.
- (1) Effects of operating temperature on electrical parameters

 At higher temperatures, leakage current and capacitance increase while equivalent series resistance (ESR) decreases.
 - b) At lower temperatures, leakage current and capacitance decrease while equivalent series resistance (ESR) decreases.
- (2) Effects of frequency on electrical parameters
 - a) At higher frequencies capacitance and impedance decrease while tand increases.
 - b) At lower frequencies, ripple current generated heat will rise due to an increase in equivalent series resistance (ESR).
- 1.2 Operating Temperature and Life Expectancy See the file: Life calculation of aluminum electrolytic capacitor
- 1.3 Common Application Conditions to Avoid

The following misapplication load conditions will cause rapid deterioration to capacitor electrical parameters. In addition, rapid heating and gas generation within the capacitor can occur causing the pressure relief vent to operate and resultant leakage of electrolyte. Under Leaking electrolyte is combustible and electrically conductive.

(1) Reverse Voltage

DC capacitors have polarity. Verify correct polarity before insertion. For circuits with changing or uncertain polarity, use DC bipolar capacitors. DC bipolar capacitors are not suitable for use in AC circuits.

(2) Charge / Discharge Applications

Standard capacitors are not suitable for use in repeating charge / discharge applications. For charge / discharge applications consult us and advise actual conditions.

(3) Over voltage

Do not apply voltages exceeding the maximum specified rated voltage. Voltages up to the surge voltage rating are acceptable for short periods of time. Ensure that the sum of the DC voltage and the superimposed AC ripple voltage does not exceed the rated voltage.

(4) Ripple Current

Do not apply ripple currents exceeding the maximum specified value. For high ripple current applications, use a capacitor designed for high ripple currents or contact us with your requirements. Ensure that allowable ripple currents superimposed on low DC bias voltages do not cause reverse voltage conditions.

- 1.4 Using Two or More Capacitors in Series or Parallel
- (1) Capacitors Connected in Parallel

The circuit resistance can closely approximate the series resistance of the capacitor causing an imbalance of ripple current loads within the capacitors. Careful design of wiring methods can minimize the possibility of excessive ripple currents applied to a capacitor.

(2) Capacitors Connected in Series

Normal DC leakage current differences among capacitors can cause voltage imbalances. The use of voltage divider shunt resistors with consideration to leakage current can prevent capacitor voltage imbalances.

- 1.5 Capacitor Mounting Considerations
- (1) Double Sided Circuit Boards

Avoid wiring pattern runs, which pass between the mounted capacitor and the circuit board.

When dipping into a solder bath, excess solder may collect under the capacitor by capillary action and short circuit the anode and cathode terminals.

(2)Circuit Board Hole Positioning

The vinyl sleeve of the capacitor can be damaged if solder passes through a lead hole for subsequently processed parts. Special care when locating hole positions in proximity to capacitors is recommended.

(3)Circuit Board Hole Spacing

The circuit board holes spacing should match the capacitor lead wire spacing within the specified tolerances. Incorrect spacing can cause excessive lead wire stress during the insertion process. This may result in premature capacitor failure due to short or open circuit, increased leakage current, or electrolyte leakage.

(4) Clearance for Case Mounted Pressure Relief vents

Capacitors with case mounted pressure relief vents require sufficient clearance to allow for proper vent operation. The minimum clearances are dependent on capacitor diameters as proper vent operation. The minimum clearances are dependent on capacitor diameters as follows.

φ6.3~φ16mm:2mm minimum, φ18~φ35mm:3mm minimum, φ40mm or greater:5mm minimum.

(5) Clearance for Seal Mounted Pressure Relief Vents

A hole in the circuit board directly under the seal vent location is required to allow proper release of pressure.

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(6) Wiring Near the Pressure Relief Vent
Avoid locating high voltage or high current wiring or circuit board paths above the pressure relief vent. Flammable, high temperature gas exceeding 100°C may be released which could dissolve the wire insulation and ignite.
(7) Circuit Board patterns Under the Capacitor
Avoid circuit board runs under the capacitor as electrolyte leakage could cause an electrical short.
(8) Screw Terminal Capacitor Mounting Do not orient the capacitor with the screw terminal side of the capacitor facing downwards.
Tighten the terminal and mounting bracket screws within the torque range specified in the specification.
1.6 Electrical Isolation of the Capacitor
Completely isolate the capacitor as follows. (1) Between the cathode and the case (except for axially leaded B types) and between the anode terminal and other circuit paths
(1) Between the extra mounting terminals (on T types) and the anode terminal, cathode terminal, and other circuit paths.
1.7 The Product endurance should take the sample as the standard.
1.8 If conduct the load or shelf life test, must be collect date code within 6 months products of sampling.
1.9 Capacitor Sleeve
The vinyl sleeve or laminate coating is intended for marking and identification purposes and is not meant to electrically insulate the capacitor.
The sleeve may split or crack if immersed into solvents such as toluene or xylene, and then exposed to high temperatures.
CAUTION!
Always consider safety when designing equipment and circuits. Plan for worst case failure modes such as short circuits and open circuits which could occur during use.
(1) Provide protection circuits and protection devices to allow safe failure modes.
(2) Design redundant or secondary circuits where possible to assure continued operation in case of main circuit failure.
2.Capacitor Handling Techniques
 2.1 Considerations Before Using (1) Consistent have a finite life. Do not much accurate consistent from used equipment.
 Capacitors have a finite life. Do not reuse or recycle capacitors from used equipment. Transient recovery voltage may be generated in the capacitor due to dielectric absorption. If required, this voltage can be discharged
with a resistor with a value of about $1k\Omega$.
(3) Capacitors stored for long periods of time may exhibit an increase in leakage current. This can be corrected by gradually applying rated voltage in series with a resistor of approximately $1k\Omega$.
 (4) If capacitors are dropped, they can be damaged mechanically or electrically. Avoid using dropped capacitors. (5) Dented or crushed capacitors should not be used. The seal integrity can be compromised and loss of electrolyte / shortened life can
(3) Dened of crushed capacitors should not be used. The sear integrity can be compromised and loss of electrolyte / shortened me can result.
2.2 Capacitor Insertion
 Verify the correct capacitance and rated voltage of the capacitor. Weify the correct capacitance and rated voltage of the capacitor.
(2) Verify the correct polarity of the capacitor before inserting.(3) Verify the correct hole spacing before insertion (land pattern size on chip type) to avoid stress on the terminals.
(4) Ensure that the auto insertion equipment lead clinching operation does not stress the capacitor leads where they enter the seal of the
capacitor. For chip type capacitors, excessive mounting pressure can cause high leakage current, short circuit, or disconnection.
r or emp type explorities, encountry pressure can cause high folkage current, short encourt, or disconnection.
2.3 Manual Soldering(1) Observe temperature and time soldering specifications or do not exceed temperatures of 400 °C for 3 seconds or less.
(1) Observe temperature and time soldering specifications of do not exceed temperatures of 400°C for 5 seconds of less. (2) If lead wires must be formed to meet terminal board hole spacing, avoid stress on the lead wire where it enters the capacitor seal.

- (3) If a soldered capacitor must be removed and reinserted, avoid excessive stress to the capacitor leads.
- (4) Avoid touching the tip of the soldering iron to the capacitor, to prevent melting of the vinyl sleeve.
- 2.4 Flow Soldering
- (1) Do not immerse the capacitor body into the solder bath as excessive internal pressure could result.
- (2) Observe proper soldering conditions (temperature, time, etc.) Do not exceed the specified limits.
- (3) Do not allow other parts or components to touch the capacitor during soldering.
- 2.5 Other Soldering Considerations

Rapid temperature rises during the preheat operation and resin bonding operation can cause cracking of the capacitor vinyl sleeve. For heat curing, do not exceed 150°C for a maximum time of 2 minutes.

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- 2.6 Capacitor Handling after Solder
- (1). Avoid movement of the capacitor after soldering to prevent excessive stress on the lead wires where they enter the seal.
- (2). Do not use capacitor as a handle when moving the circuit board assembly.
- (3). Avoid striking the capacitor after assembly to prevent failure due to excessive shock.
- 2.7 Circuit Board Cleaning

Acetone

- (1) Circuit boards can be immersed or ultrasonically cleaned using suitable cleaning solvents for up 5 minutes and up to 60°C maximum temperatures. The boards should be thoroughly rinsed and dried. The use of ozone depleting cleaning agents is not recommended in the interest of protecting the environment.
- (2) Avoid using the following solvent groups unless specifically allowed for in the specification;

Halogenated cleaning solvents: except for solvent resistant capacitor types, halogenated solvents can permeate the seal and cause internal capacitor corrosion and failure. For solvent resistant capacitors, carefully follow the temperature and time requirements of the specification. 1-1-1 trichloroethane should never be used on any aluminum electrolytic capacitor.

- Alkali solvents : could attack and dissolve the aluminum case.
- Petroleum based solvents: deterioration of the rubber seal could result.
- Xylene : deterioration of the rubber seal could result.
 - : removal of the ink markings on the vinyl sleeve could result.
- (3) A thorough drying after cleaning is required to remove residual cleaning solvents which may be trapped between the capacitor and the circuit board. Avoid drying temperatures, which exceed the maximum rated temperature of the capacitor.
- (4) Monitor the contamination levels of the cleaning solvents during use by electrical conductivity, pH, specific gravity, or water content. Chlorine levels can rise with contamination and adversely affect the performance of the capacitor. Please consult us for additional information about acceptable cleaning solvents or cleaning methods.

2.8 Mounting Adhesives and Coating Agents

When using mounting adhesives or coating agents to control humidity, avoid using materials containing halogenated solvents. Also, avoid the use of chloroprene based polymers. After applying adhesives or coatings, dry thoroughly to prevent residual solvents from being trapped between the capacitor and the circuit board.

3. Precautions for using capacitors

3.1 Environmental Conditions

- Capacitors should not be stored or used in the following environments.
- (1) Temperature exposure above the maximum rated or below the minimum rated temperature of the capacitor.
- (2) Direct contact with water, salt water, or oil.
- (3) High humidity conditions where water could condense on the capacitor.
- (4) Exposure to toxic gases such as hydrogen sulfide, sulfuric acid, nitric acid chlorine, or ammonia.
- (5) Exposure to ozone, radiation, or ultraviolet rays.
- (6) Vibration and shock conditions exceeding specified requirements.

3.2 Electrical Precautions

- (1) Avoid touching the terminals of the capacitor as possible electric shock could result. The exposed aluminum case is not insulated and could also cause electric shock if touched.
- (2) Avoid short circuit the area between the capacitor terminals with conductive materials including liquids such as acids or alkaline solutions.

4. Emergency Procedures

- (1) If the pressure relief vent of the capacitor operates, immediately turn off the equipment and disconnect form the power source. This will minimize additional damage caused by the vaporizing electrolyte.
- (2) Avoid contact with the escaping electrolyte gas which can exceed 100°C temperatures.

If electrolyte or gas enters the eye, immediately flush the eyes with large amounts of water.

If electrolyte or gas is ingested by month, gargle with water.

If electrolyte contacts the skin, wash with soap and water.

5. Long Term Storage

Leakage current of a capacitor increases with long storage times. The aluminum oxide film deteriorates as a function of temperature and time. If used without reconditioning, an abnormally high current will be required to restore the oxide film. This current surge could cause the circuit or the capacitor to fail. After one year, a capacitor should be reconditioned by applying rated voltage in series with a 1000Ω , current limiting resistor for a time period of 30 minutes. If the expired date of products date code is over eighteen months, the products should be return to confirmation.

5.1 Environmental Conditions

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The capacitor shall be not use in the following condition:

(1) Temperature exposure above the maximum rated or below the minimum rated temperature of the capacitor.

(2) Direct contact with water, salt water, or oil.

(3) High humidity conditions where water could condense on the capacitor.

(4) Exposure to toxic gases such as hydrogen sulfide, sulfuric acid, nitric acid, chlorine, or ammonia.

(5) Exposure to ozone, radiation, or ultraviolet rays.

(6) Vibration and shock conditions exceeding specified requirements.

6. Capacitor Disposal

When disposing of capacitors, use one of the following methods.

Incinerate after crushing the capacitor or puncturing the can wall (to prevent explosion due to internal pressure rise). Capacitors should be incinerated at high temperatures to prevent the release of toxic gases such as chlorine from the

polyvinyl chloride sleeve, etc.

Dispose of as solid waste.

NOTE: Local laws may have specific disposal requirements, which must be followed.

Remark:5G power system is not applicable

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